

MOS FIELD EFFECT TRANSISTOR 2SK3295

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

DESCRIPTION

The 2SK3295 is N-Channel MOS FET device that features a low on-state resistance and excellent switching characteristics, designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

FEATURES

- 4.5 V drive available
- · Low on-state resistance

RDS(on)1 = 18 m Ω MAX. (VGS = 10 V, ID = 18 A)

Low gate charge

 $Q_G = 16 \text{ nC TYP}$. ($I_D = 35 \text{ A}$, $V_{DD} = 16 \text{ V}$, $V_{GS} = 10 \text{ V}$)

- Built-in gate protection diode
- Surface mount device available

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Vos = 0 V)	VDSS	20	V
Gate to Source Voltage (Vps = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±35	Α
Drain Current (Pulse) Note	D(pulse)	±140	Α
Total Power Dissipation (T _A = 25°C)	P _{T1}	1.5	W
Total Power Dissipation (Tc = 25°C)	P _{T2}	35	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +150	°C

Note PW \leq 10 μ s, Duty Cycle \leq 1%

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3295	TO-220AB
2SK3295-S	TO-262
2SK3295-ZK	TO-263(MP-25ZK)
2SK3295-ZJ	TO-263(MP-25ZJ)

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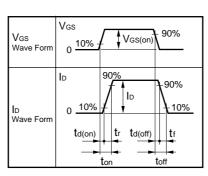


ELECTRICAL CHARACTERISTICS(TA = 25°C)

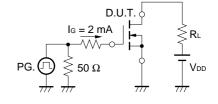
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	loss	V _{DS} = 20 V, V _{GS} = 0 V			10	μΑ
Gate Leakage Current	Igss	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.0		2.5	V
Forward Transfer Admittance	yfs	V _{DS} = 10 V, I _D = 18 A	7.5			S
Drain to Source On-state Resistance	R _{DS(on)1}	Vgs = 10 V, ID = 18 A		13	18	mΩ
	R _{DS(on)2}	Vgs = 4.5 V, lp = 18 A		21	27	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V		720		pF
Output Capacitance	Coss	Vgs = 0 V		370		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		180		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 10 V , I _D = 18 A		85		ns
Rise Time	tr	V _{GS(on)} = 10 V		2000		ns
Turn-off Delay Time	td(off)	R _G = 10 Ω		65		ns
Fall Time	t _f			270		ns
Total Gate Charge	Q _G	V _{DD} = 16 V		16		nC
Gate to Source Charge	Qgs	Vgs = 10 V		3.1		nC
Gate to Drain Charge	Q _{GD}	I _D = 35 A		5.2		nC
Body Diode Forward Voltage	VF(S-D)	IF = 35 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 35 A, VGS = 0 V		28		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		14		nC

TEST CIRCUIT 1 SWITCHING TIME

PG. 0 $\tau = 1 \mu s$ Duty Cycle $\leq 1\%$

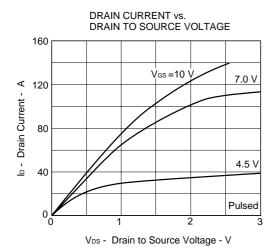


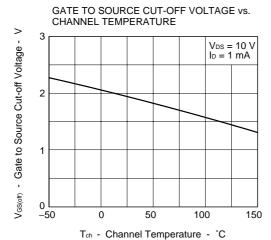
TEST CIRCUIT 2 GATE CHARGE

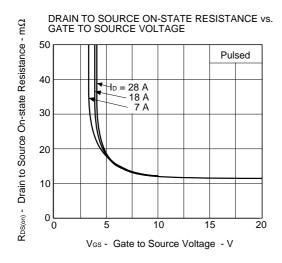




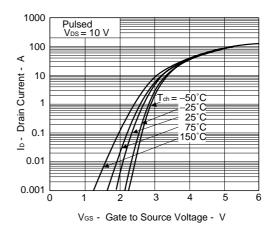
TYPICAL CHARACTERISTICS (TA = 25°C)



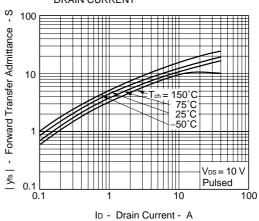




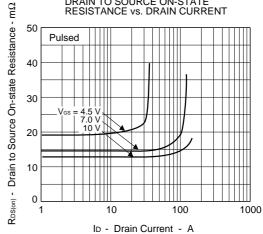
FORWARD TRANSFER CHARACTERISTICS

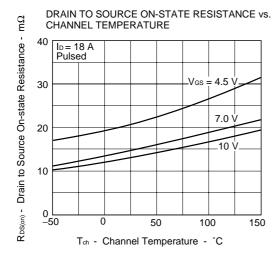


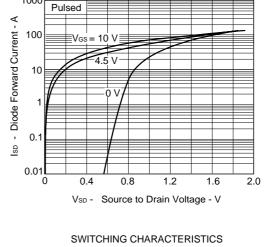
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT







SOURCE TO DRAIN DIODE

FORWARD VOLTAGE

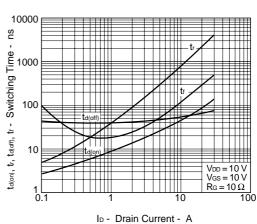
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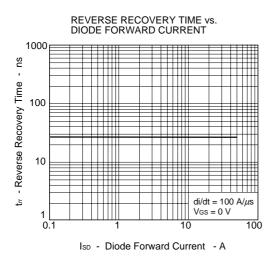
V_{DS} - Drain to Source Voltage - V

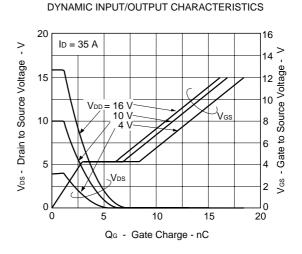
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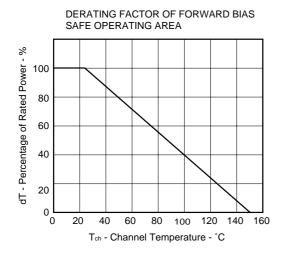
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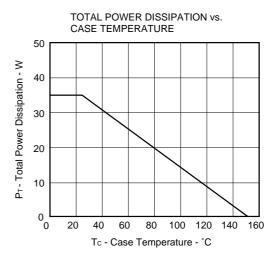
10 L 0.1



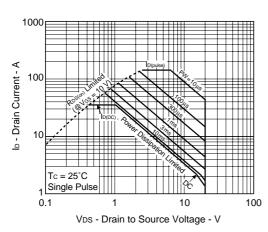




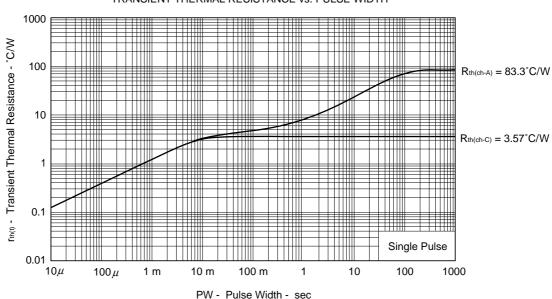




★ FORWARD BIAS SAFE OPERATING AREA



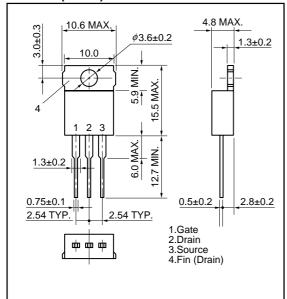
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



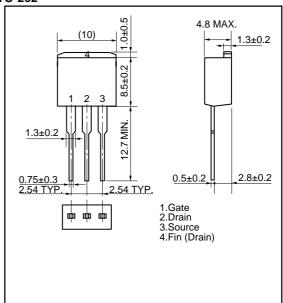
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PACKAGE DRAWINGS (Unit: mm)

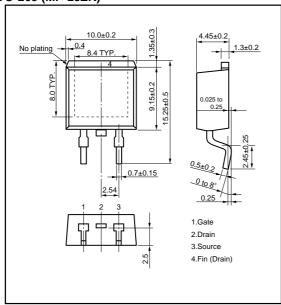
1)TO-220AB (MP-25)



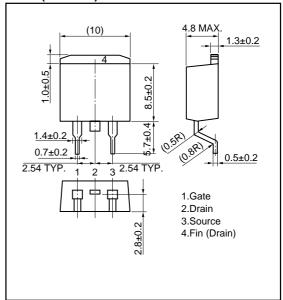
2)TO-262



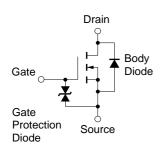
3)TO-263 (MP-25ZK)



4)TO-263 (MP-25ZJ)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD.

> When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

NEC 2SK3295

[MEMO]

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